

RB521S

List

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings and Electrical characteristics	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6
High reliability test capabilities.....	7

RB521S

200mA Surface Mount Small Signal Schottky Diodes 30V

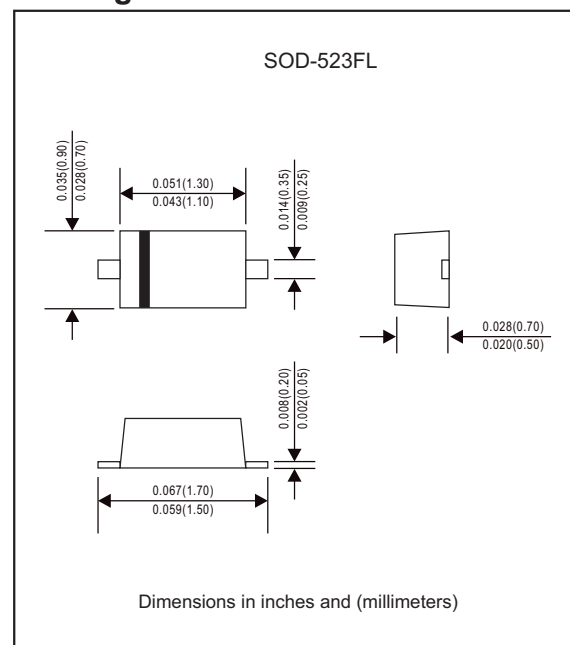
Features

- Low current rectification and high speed switching
- Extremely small surface mount type
- Up to 200mA current capability
- Low forward voltage drop (V_F max 0.5V @ $I_F=200\text{mA}$)
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free parts, ex. RB521S-H

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-523FL
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.002 gram

Package outline



Maximum ratings (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	Unit
Repetitive peak reverse voltage		V_{RM}			30	V
DC reverse voltage		V_R			30	V
Mean rectifying current		I_o			200	mA
Total power dissipation	FR-5 Board (Note 1) @ $T_A=25^\circ\text{C}$	P_D			200	mW
Peak forward surge current	60Hz for 1cycle	I_{FSM}			1000	mA
Thermal resistance	Junction to ambient (Note 1) Junction to case (Note 1)	$R_{\theta JA}$ $R_{\theta JC}$		500 375		$^\circ\text{C/W}$ $^\circ\text{C/W}$
Operating junction temperature range		T_J	-40		+125	$^\circ\text{C}$
Storage temperature range		T_{STG}	-40		+125	$^\circ\text{C}$

Note 1: FR-5=1.0×0.75×0.062 in

Electrical characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	Unit
Forward voltage	$I_F=200\text{mA}$	V_F			0.5	V
Reverse current	$V_R=10\text{V}$	I_R			30	μA
Diode capacitance	$V_R=10\text{V}$, $f=1\text{MHz}$	C_T		4.0		pF

Rating and characteristic curves (RB521S)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

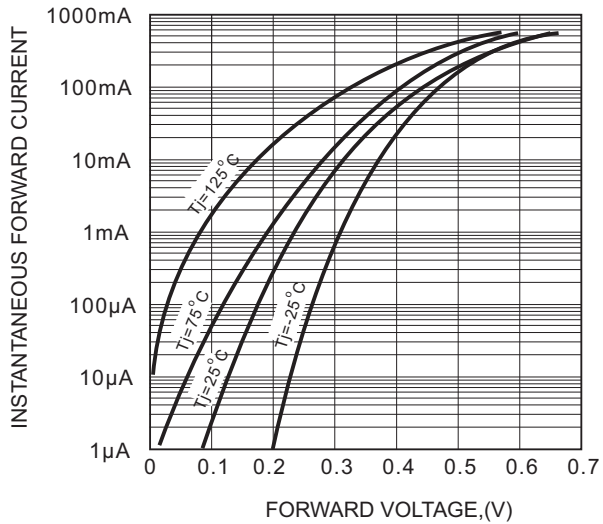


FIG.2 - TYPICAL REVERSE CHARACTERISTICS

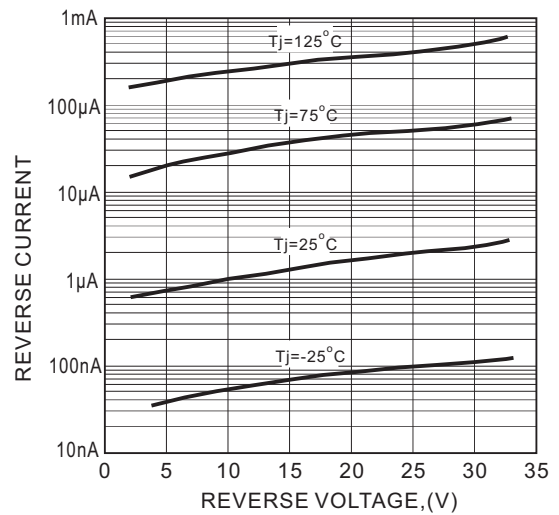


FIG.3-TYPICAL TERMINALS CAPACITANCE

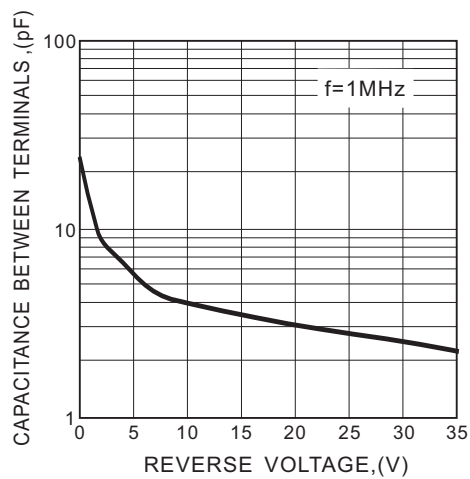
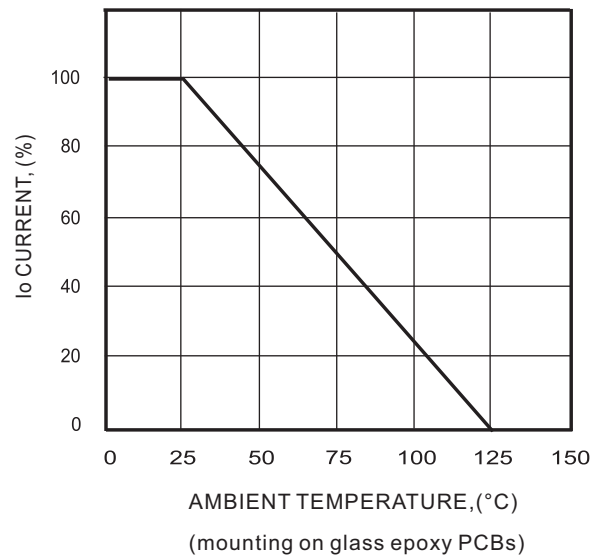


FIG.4- DERATING CURVE



RB521S

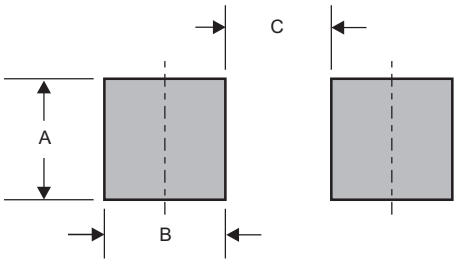
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
RB521S	C, 5M

Suggested solder pad layout

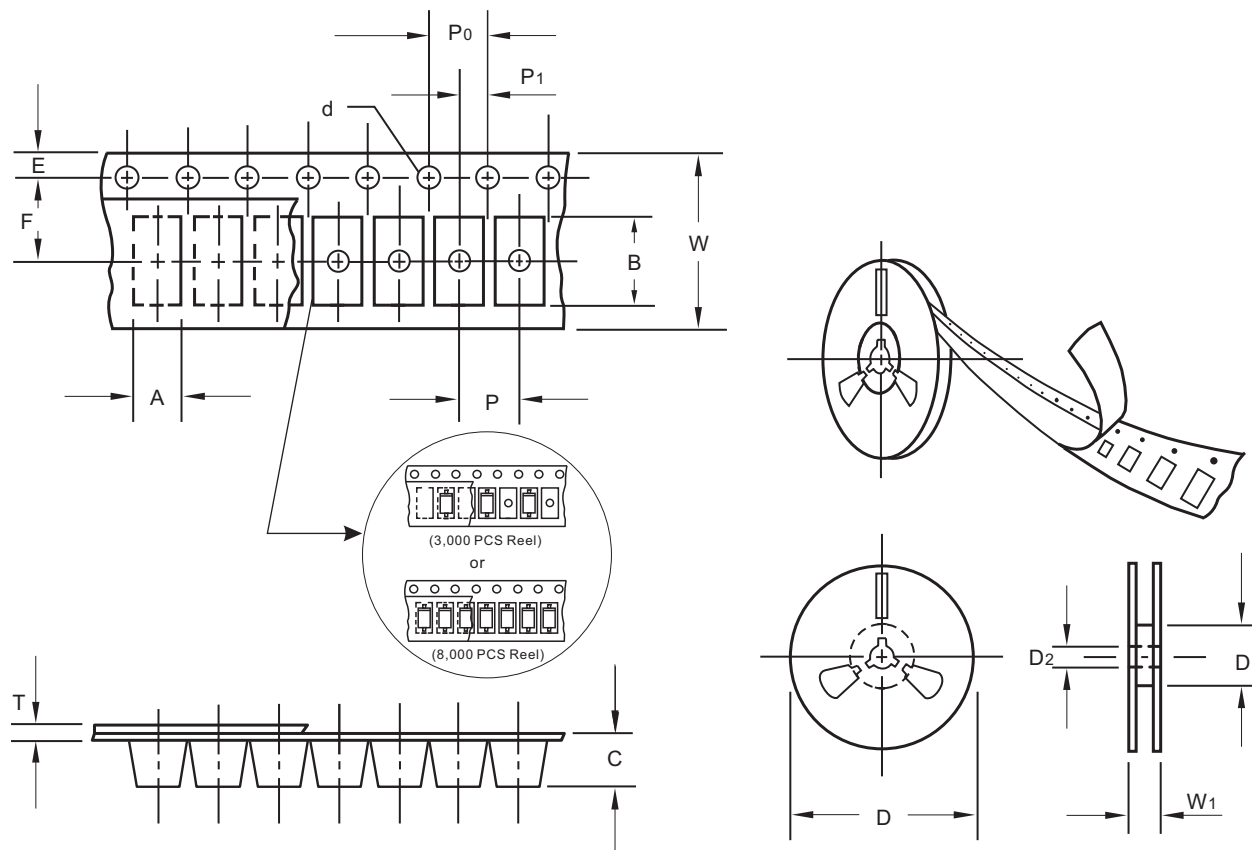


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-523FL	0.032 (0.80)	0.024 (0.60)	0.044 (1.10)

RB521S

Packing information



unit:mm

Item	Symbol	Tolerance	SOD-523FL
Carrier width	A	0.1	0.90
Carrier length	B	0.1	1.94
Carrier depth	C	0.1	0.76
Sprocket hole	d	0.1	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	50.00
Feed hole diameter	D ₂	0.2	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	9.50

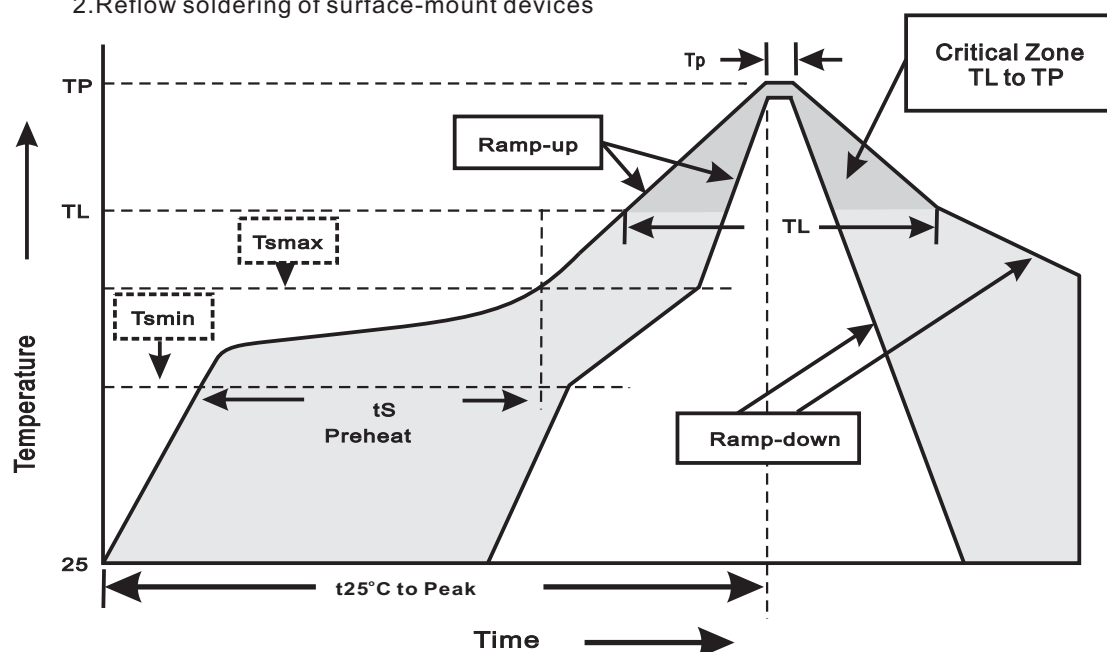
Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

RB521S**Reel packing**

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-523FL	7"	3,000	2.0	30,000	183*123*183	178	382*257*387	240,000	8
		8,000	2.0	80,000	183*123*183	178	382*257*387	640,000	10

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices

**3.Reflow soldering**

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

RB521S

High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^{\circ}\text{C}$ for $10 \pm 2\text{sec.}$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	60Hz for 1cycle	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031